



0.5A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

FEATURES:

- Glass Passivated Chip Junction
- Reverse Voltage - 600V
- Forward Current - 0.5 A
- High Surge Current Capability
- Designed for Surface Mount Application

PINNING

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)



MBF Package

MECHANICAL DATA

- Case: MBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 75mg 0.0026oz

Maximum Ratings and Electrical characteristics

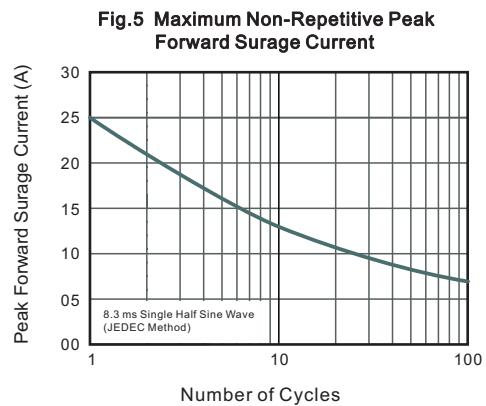
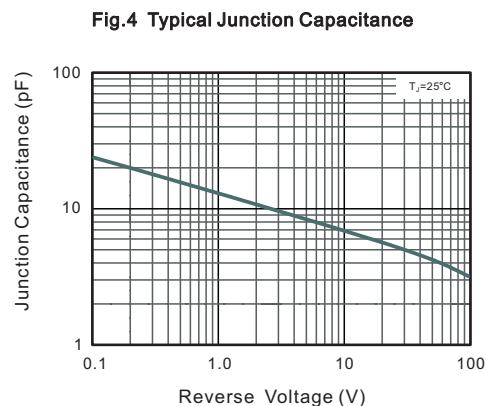
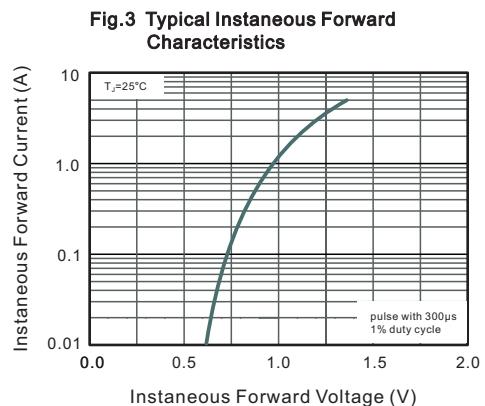
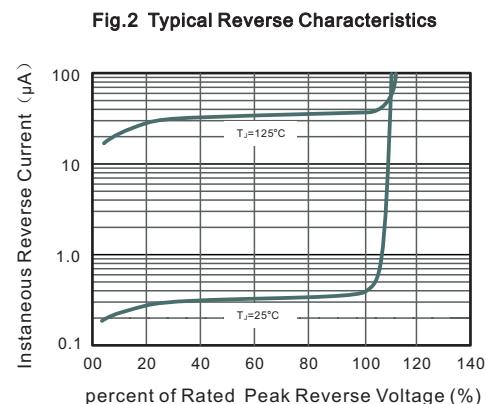
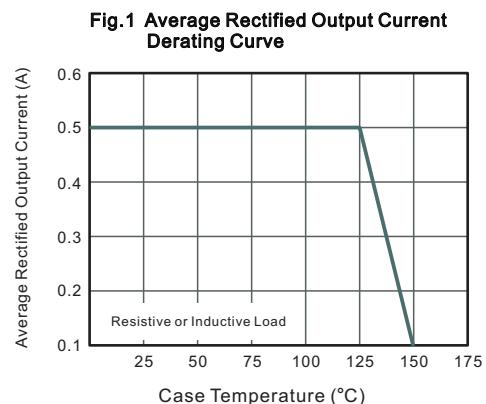
Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	MB6FB	Units
Maximum Repetitive Peak Reverse Voltage	V_{RMM}	600	V
Maximum RMS voltage	V_{RMS}	420	V
Maximum DC Blocking Voltage	V_{DC}	600	V
Average Rectified Output Current at $T_c = 125^\circ\text{C}$	I_O	0.5	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	25 (TYPE)	A
Maximum Forward Voltage at 0.5 A	V_F	1.0	V
Maximum DC Reverse Current @ $T_A = 25^\circ\text{C}$ @ $T_A = 125^\circ\text{C}$	I_R	5 40	μA
Typical Junction Capacitance (Note1)	C_j	9	pF
Typical Thermal Resistance (Note2)	$R_{\theta JA}$	110	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	$^\circ\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

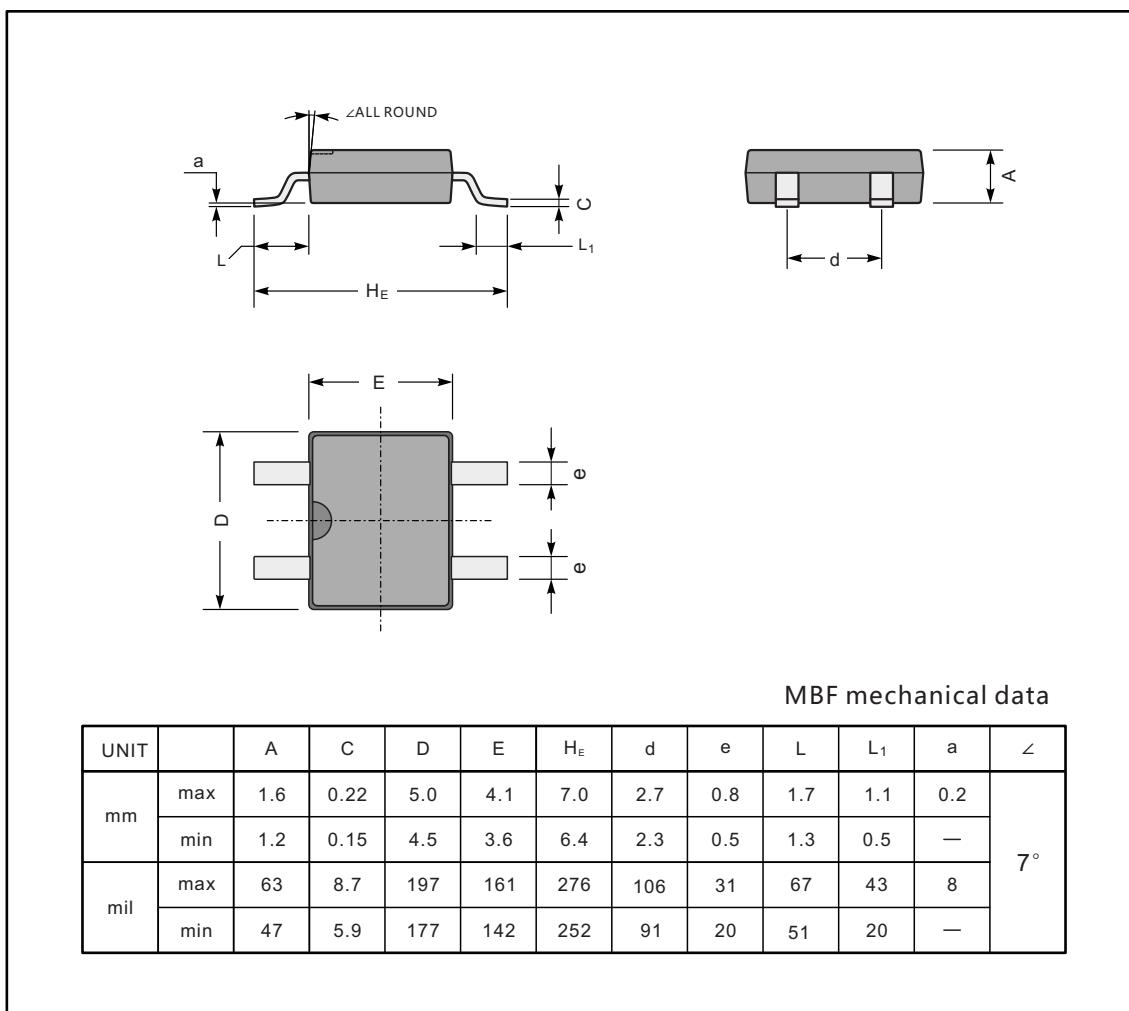




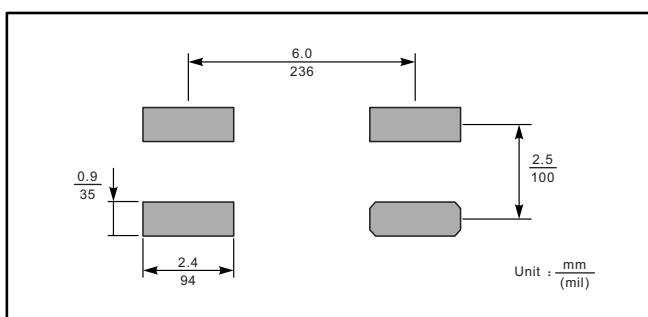
PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

MBF



The recommended mounting pad size



Marking

Type number	Marking code
MB6FB	M6FB